

GBU608

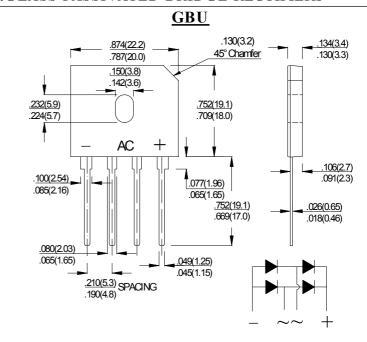
SINGLE PHASE 6.0 AMPS. GLASS PASSIVATED BRIDGE RECTIFIERS

FEATURE

- . Ideal for printed circuit board
- . Glass passivated chip junctions
- . High case dielectric strength
- . Low leakage
- . Low forward voltage
- . High surge current capability
- . High temperature soldering guaranteed: 260°C/10seconds/.375",(9.5mm) lead lengths.

MECHANICAL DATA

- . Case: Molded plastic body
- . Epoxy: UL 94V-0 rate flame retardant
- Terminals: Pure tin plated, Lead free. Leads solderable per MIL-STD-750, Method 2026.
- . Polarity: Symbols molded or marked on body
- . Mounting position: Any



Dimensions in millimeters

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

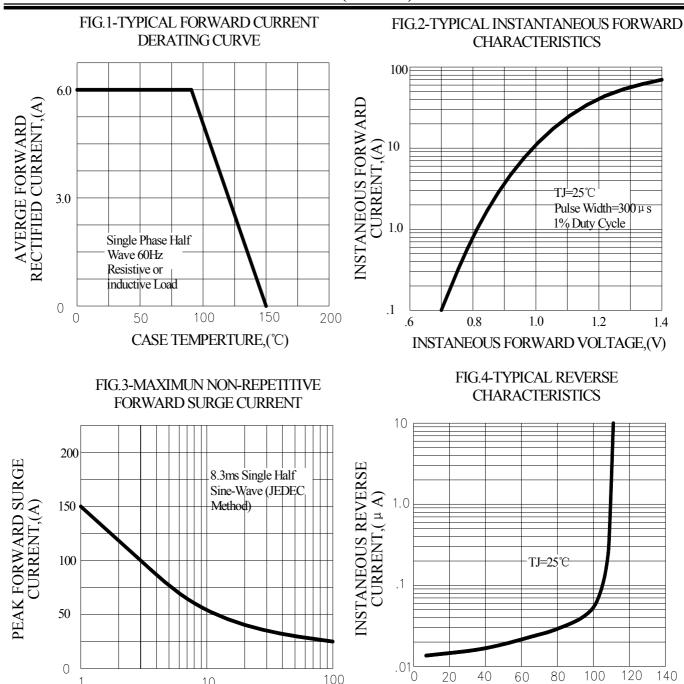
For capacitive load, derate current by 20%

Type Number	SYM BOL	GBU608	units
Maximum Recurrent Peak Reverse Voltage	$V_{ m RRM}$	800	V
Maximum RMS Voltage	$V_{ m RMS}$	560	V
Maximum DC blocking Voltage	$V_{ m DC}$	800	V
Maximum Average Forward rectified Output Current at T_C =90°C	$I_{ m F(AV)}$	6.0	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rate load (JEDEC method)	I_{FSM}	150	A
Maximum Forward Voltage Drop per element at 6.0A DC	$V_{ m F}$	1.1	V
Maximum DC Reverse Current @T _A =25°C at rated DC blocking voltage @T _A =125°C	$I_{ m R}$	10.0 500.0	μА
I ² t Rating for Fusing (t < 8.3ms)	I^2 t	93	A ² Sec
Typical Junction Capacitance (Note 1)	$C_{ m J}$	45	pF
Typical Thermal Resistance (Note 2)	$R_{(JC)}$	2.2	°C/W
Storage Temperature	T _{STG}	-55 to +150	°C
Operating Junction Temperature	$T_{ m J}$	-55 to +150	°C

Note:

- 1. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
- 2. Thermal Resistance from Junction to Case Mounted on P.C.B with 0.47×0.47" (12×12mm) Copper Pads.

RATING AND CHARACTERISTIC CURVES (GBU608)



100

PERCENT OF RATED PEAK REVERSE

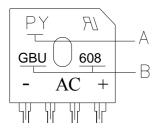
VOLTAGE,(%)

10

NUMBER OF CYCLES AT 60Hz

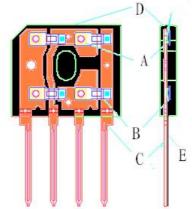
Marking and packaging illustration

1. Marking



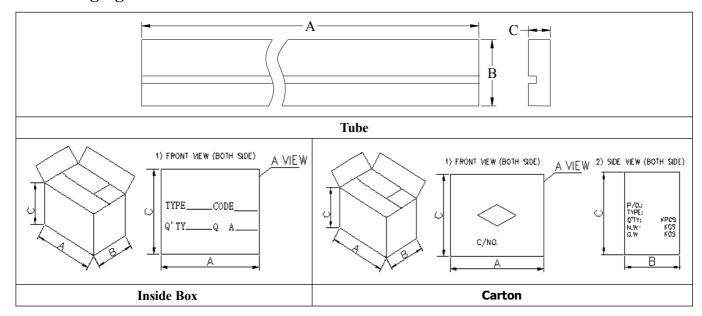
SYMBOL	Explanation
A	Trademark
В	Product Name

2. Structure



SYMBOL	Explanation	
1	Dice	
2	Solder	
3	Lead Wire	
4	Epoxy Compound	
5	Plating	

3. Packaging



OUTLINE	A (mm)	B (mm)	C (mm)
Tube	470 ± 1	41±1	7.0 \pm 1
Inner box	478±3	48±3	175±3
Carton	496±5	185±5	220±5

COUNT	TUBE (PCS)	BOX (PCS)	CARTON(PCS)
GBU	20	400	2800